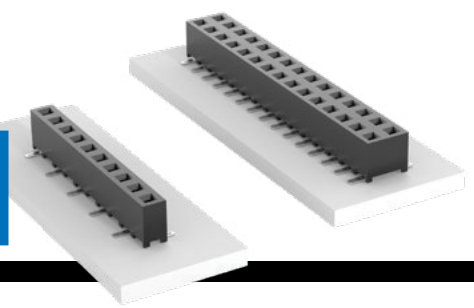




SMM	1	NO. PINS PER ROW	02	PLATING OPTION	ROW OPTION	OTHER OPTIONS
		02 thru 40		-F = Gold flash on contact, Matte Tin on tail -L = 10 μ " (0.25 μ m) Gold on contact, Matte Tin on tail -S = 30 μ " (0.76 μ m) Gold on contact, Matte Tin on tail	-S = Single Row -D = Double Row	-XX = Polarized Position -K = (5.50 mm) .217" DIA Polyimide Film Pick & Place Pad (2 positions minimum, -02 thru -05 requires -TR) -P = Plastic Pick & Place Pad (-02 thru -05 requires -TR) -TR = Tape & Reel Packaging (27 positions maximum) -FR = Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks) (27 positions maximum)

SMM

Board Mates:

TMM, TMMH, MTMM, MMT, LTMM, TW, PTT, ZLTMM

Cable Mates:

TCMD

SPECIFICATIONS

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

BeCu

Plating:

Sn or Au over

50 μ " (1.27 μ m) Ni

Current Rating (TMM/SMM):

3.2 A per pin

(2 pins powered)

Voltage Rating:

350 VAC

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

(3.05 mm) .120" to

(3.25 mm) .128"

Max Cycles:

100 with 10 μ " (0.25 μ m) Au

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max

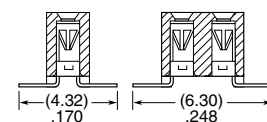
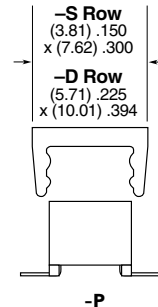
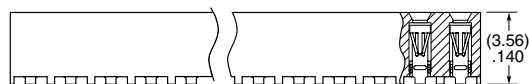
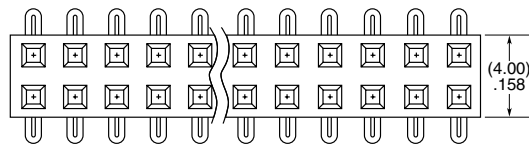
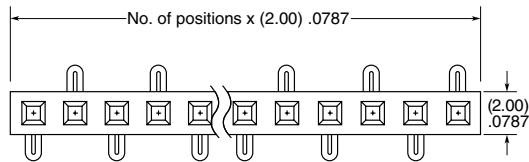
ALSO AVAILABLE

MOQ Required

Locking Clip

(Manual placement required)

Other platings



Note:

Some lengths, styles and options are non-standard, non-returnable.

View complete specifications at: samtec.com?SMM